



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Kinsman et al.

**Serial No.:** 09/538,684

**Filed:** March 30, 2000

**For:** VARIED-THICKNESS HEAT SINK  
FOR INTEGRATED CIRCUIT (IC)  
PACKAGES AND METHOD OF  
FABRICATING IC PACKAGES

**Confirmation No.:** 8722

**Examiner:** D. Graybill

**Group Art Unit:** 2827

**Attorney Docket No.:** 3056.1US (96-803.1)

CERTIFICATE OF MAILING

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RESPONSE TO FINAL OFFICE ACTION

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This reply is sent in response to the Final Rejection of the claimed invention in the Office Action of October 22, 2002, whose timely period of response occurs on December 22, 2002, and whose initial period of response is set to expire on January 22, 2003.